

RZ/N2L Group

Release Note for RZ/N2L Example Program V3.0.0

Introduction

This is the release note for example program using Flexible Software Package (FSP) running on Arm® Cortex®-R52 core of RZ/N2L.

Target Device

RZ/N2L

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1. Release Notes

Example program using Flexible Software Package (FSP) for Renesas RZ/N2L.

2. Deliverables

Deliverables	Example program using FSP for RZ/N2L (Ver 3.0.0)
Files	r01an6538ej0300-rzn2l-example-program-package.zip
	<i>This zip file contains this documentation and example programs.</i>
	r01an6538ej0300-rzn2l-example-program-package.pdf
	<i>This documentation. It is included in the above zip file.</i>

3. Tools

Development environment (EWARM)

◇Flexible Software Package(FSP) for RZ/N2 v3.0.0

◇IDE: Embedded Workbench® for Arm (EWARM)

• Version 9.60.3

◇FSP Smart Configurator (FSP SC) 2025-04.1

◇Debug probe

• IAR I-jet

Development environment (e² studio)

◇Flexible Software Package(FSP) for RZ/N2 v3.0.0

◇IDE: e² Studio 2025-04.1

• Toolchain version

- GNU ARM Embedded: 13.3.1.arm-13-24

◇Debug probe

• Segger J-Link OB

4. Features

The following table lists Modules used by example program. “File name” in bold are added/updated example programs.

Mainly used module name	Example program file name
Analog to Digital Converter (r_adc)	RZN2L_RSK_adc_Rev300.zip
Bus State Controller (r_bsc)	RZN2L_RSK_bsc_Rev300.zip
Bus State Controller (BSC) SDRAM (r_bsc_sdram)	RZN2L_RSK_bsc_sdram_Rev300.zip
Controller Area Network – Flexible Data (r_canfd)	RZN2L_RSK_canfd_Rev300.zip
Clock Generation Circuit (r_cgc)	RZN2L_RSK_cgc_Rev300.zip
Compare Match Timer (r_cmt)	RZN2L_RSK_cmt_Rev300.zip
Compare Match Timer W (r_cmtw)	RZN2L_RSK_cmtw_Rev300.zip
Direct Memory Access Controller (r_dmac)	RZN2L_RSK_dmac_Rev300 .zip
Delta-sigma interface (r_dsmif)	RZN2L_RSK_dsmif_gpt_poeg_Rev300.zip
General PWM Timer (r_gpt)	
Port Output Enable for GPT (r_poeg)	
Event Link Controller (r_elc)	RZN2L_RSK_elc_Rev300.zip
Ethernet (r_ether)	RZN2L_RSK_Ethernet_Rev300.zip
Ethernet PHY (r_ether_phy)	
Ethernet SWITCH (r_ether_switch)	
Ethernet SELECTOR (r_ether_selector)	
FreeRTOS Port (rm_freertos_port)	RZN2L_RSK_FreeRTOS_Rev300.zip
FreeRTOS Plus TCP (rm_Freertos_plus_tcp)	RZN2L_RSK_FreeRTOSplusTCP_Rev300.zip
General PWM Timer (r_gpt)	RZN2L_RSK_gpt_phase_count_Rev300.zip
Expanded Serial Peripheral Interface (xSPI) HyperBus (r_xspi_hyper)	RZN2L_RSK_HyperRAM_Rev300.zip
I2C Master on IIC (r_iic_master)	RZN2L_RSK_iic_master_Rev300.zip RZN2L_RSK_iic_master_dmac_Rev300
I2C Slave on IIC (r_iic_slave)	RZN2L_RSK_iic_slave_Rev300.zip
Multi-Function Timer Pulse Unit 3 (r_mtu3)	RZN2L_RSK_mtu3_phase_count_Rev300.zip
Multi-Function Timer Pulse Unit 3 (r_mtu3)	RZN2L_RSK_mtu3_poe3_Rev300.zip
Port Output Enable 3 (r_poe3)	
Multi-Function Timer Pulse Unit 3 (r_mtu3)	RZN2L_RSK_mtu3_Rev300.zip
Serial Communications Interface (SCI) UART (r_scif_uart)	RZN2L_RSK_sci_uart_Rev300.zip RZN2L_RSK_sci_uart_dmac_Rev300.zip
Serial Peripheral Interface (r_spi)	RZN2L_RSK_spi_Rev300.zip RZN2L_RSK_spi_dmac_Rev300.zip
USB (r_usb_basic)	RZN2L_RSK_usb_hcdc_Rev300.zip
USB Host Communications Device Class Driver (r_usb_hcdc)	
USB Host Human Interface Device Class Driver (r_usb_hhid)	RZN2L_RSK_usb_hhid_Rev300.zip
USB (r_usb_basic)	RZN2L_RSK_usb_hmsc_Rev300.zip
USB Host Mass Storage Class Driver (r_usb_hmsc)	
USB Host Vendor class (r_usb_hvnd)	RZN2L_RSK_usb_hvnd_Rev300.zip
USB (r_usb_basic)	RZN2L_RSK_usb_pcdc_Rev300.zip
USB Peripheral Communications Device Class (r_usb_pcdc)	
USB Peripheral Mass Storage Class (r_usb_pmsc)	RZN2L_RSK_usb_pmsc_Rev300.zip

USB Peripheral Vendor class (r_usb_pvnd)	RZN2L_RSK_usb_pvnd_Rev300.zip
Expanded Serial Peripheral Interface (xSPI) OSPI (r_xspi_ospi)	RZN2L_RSK_xspi_ospi_Rev300.zip
Expanded Serial Peripheral Interface (xSPI) QSPI (r_xspi_qspi)	RZN2L_RSK_xspi_qspi_Rev300.zip RZN2L_RSK_xspi_qspi_xip_Rev300.zip

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Aug.9,22	-	First Edition issued.
1.10	Oct.3,22	2	Changed package file name for version changing. Changed patch file for EWARM 9.30.1. --- EWARM_Patch_for_RZN2L_rev1.1.zip
		3	Added following example programs. --- RZN2L_RSK_iic_master_dmac_Rev100.zip --- RZN2L_RSK_sci_uart_dmac_Rev100.zip --- RZN2L_RSK_spi_dmac_Rev100.zip Changed following file name. --- RZN2L_RSK_xspi_ospi_Rev100.zip --- RZN2L_RSK_xspi_qspi_Rev100.zip Update following example program. --- RZN2L_RSK_FreeRTOSplusTCP_Rev110.zip
1.20	Apr.28,23	2	Changed package file name for version changing.
		3	Added following example program. --- RZN2L_RSK_bsc_sdram_Rev100.zip --- RZN2L_RSK_usb_hmsc_Rev100.zip Updated following example program. --- RZN2L_RSK_dsmif_gpt_poeg_Rev110.zip --- RZN2L_RSK_mtu3_poe3_Rev110.zip --- RZN2L_RSK_sci_uart_Rev110.zip --- RZN2L_RSK_sci_uart_dmac_Rev110.zip --- RZN2L_RSK_usb_pcdc_Rev110.zip
1.30	Aug.04,23	2	Changed package file name for version changing.
		3	Added following example program. --- RZN2L_RSK_HyperRAM_Rev100.zip Updated following example program. --- RZN2L_RSK_canfd_Rev110.zip --- RZN2L_RSK_dsmif_gpt_poeg_Rev110.zip --- RZN2L_RSK_xspi_ospi_Rev110.zip --- RZN2L_RSK_xspi_qspi_Rev110.zip --- RZN2L_RSK_Ethernet_Rev110.zip --- RZN2L_RSK_FreeRTOSplusTCP_Rev120.zip --- RZN2L_RSK_mtu3_poe3_Rev120.zip --- RZN2L_RSK_usb_hcdc_Rev120.zip --- RZN2L_RSK_usb_hmsc_Rev110.zip --- RZN2L_RSK_usb_pcdc_Rev120.zip

Rev.	Date	Description	
		Page	Summary
1.40	Dec.18,23	3	Added following example program. --- RZN2L_RSK_FreeRTOS_Rev100.zip --- RZN2L_RSK_usb_hhid_Rev100.zip --- RZN2L_RSK_usb_pmsc_Rev100.zip --- RZN2L_RSK_xspi_qspi_xip_Rev100.zip Updated following example program. --- RZN2L_RSK_Ethernet_Rev120.zip
2.00	Aug. 22, 24	2,3,4	Updated for FSP v2.0.0
3.00	Dec.3, 2025	-	Added following example program. --- RZN2L_RSK_usb_hvnd_Rev300.zip --- RZN2L_RSK_usb_pvnd_Rev300.zip Updated All example program for RZ/N2 FSP v3.0.0

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity.

Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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